



PATENT ABSTRACTS OF JAPAN

(11) Publication number: **03227229 A**(43) Date of publication of application: **08.10.91**

(51) Int. Cl.

B32B 5/18
B32B 7/02
B32B 27/32
// B29C 61/06
B29K 23:00
B29K105:02
B29L 9:00

(21) Application number: **02023235**(22) Date of filing: **31.01.90**(71) Applicant: **SEKISUI PLASTICS CO LTD**(72) Inventor: **TSUBONE TADAYASU**
AMANO NORIO(54) **HEAT-SHRINKABLE SHEET**

(57) Abstract:

PURPOSE: To enhance heat resistance, heat shrinkability, printability, shock-absorbing properties and stiffness and enable suitable use for shrink packaging, by laminating a foamed sheet of a heat-shrinkable polyolefin resin and a non-foamable film, incorporating a specified amount of an inorganic filler in the foamed sheet, and adding a solvent-soluble resin to the non-foamable film.

CONSTITUTION: A foamed sheet of a heat-shrinkable polyolefin resin and a non-foamable film are laminated with each other. An inorganic filler is incorporated in the foamed sheet by an amount of 5-40wt.%, thereby

enhancing thermal conductivity, heat shrink properties and heat resistance. The foamed sheet has a minutely rugged rough surface, which ensures firm adhesion to the non-foamable film. Since printability and stiffness or the like are also enhanced, workability in using the laminated sheet for shrink packaging is enhanced. A solvent-soluble resin is added to the non-foamable film, whereby the sheet is provided with a minutely rugged rough surface, leading to enhanced printability and adhesive properties. The coefficient of heat shrinkage of the heat-shrinkable sheet is preferably at least 15% in one direction and -10 to 10% in the orthogonal direction, under heating conditions of 150°C and 15sec.

COPYRIGHT: (C)1991,JPO&Japio